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Kim et al.

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(54) **ORGANIC LIGHT EMITTING DISPLAY
DEVICE WITH INSULATING PART AND
METHOD OF MANUFACTURING THE SAME**

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H01L 27/3258; H01L 51/5203; H01L
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See application file for complete search history.

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H01L 27/32 (2006.01)

(52) **U.S. Cl.**

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2251/5392 (2013.01); **H01L 2251/558**
(2013.01); **H01L 2251/568** (2013.01)

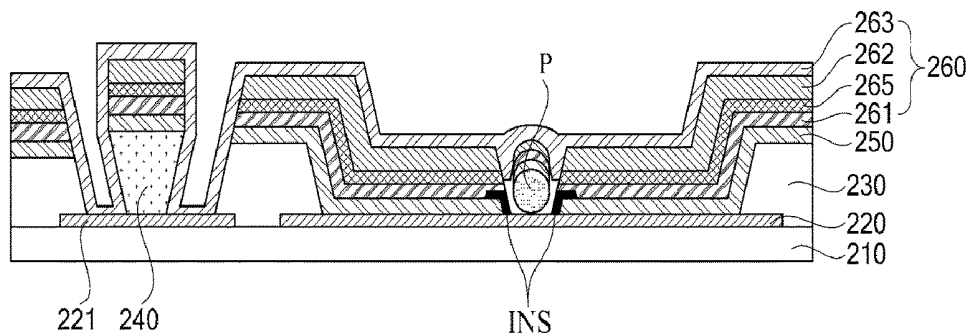
(58) **Field of Classification Search**

CPC H01L 27/3246; H01L 27/3244; H01L
27/1255; H01L 51/5012; H01L

(57) **ABSTRACT**

Disclosed is an organic light emitting display device. The organic light emitting display device includes a substrate, a pixel electrode disposed on the substrate, an organic emission layer disposed on the pixel electrode, a common electrode including a metal layer disposed on the organic emission layer, a conductive organic layer disposed on the metal layer, and a first metal oxide layer disposed on the conductive organic layer, and an insulating part formed in a part of an area of a surface of the metal layer which is exposed to a foreign material. The insulating part insulates the pixel electrode from the common electrode.

20 Claims, 4 Drawing Sheets



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FIG. 1
RELATED ART

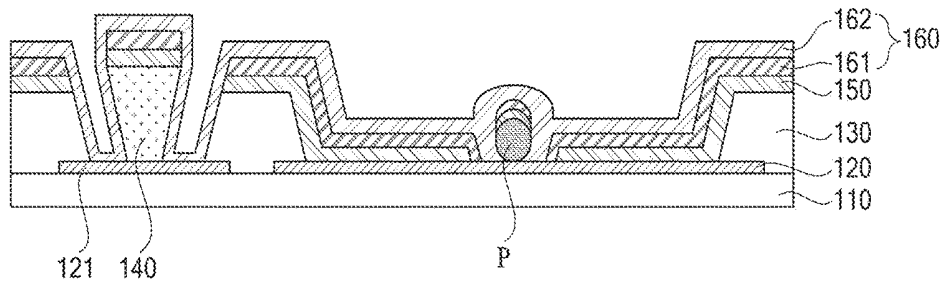


FIG. 2

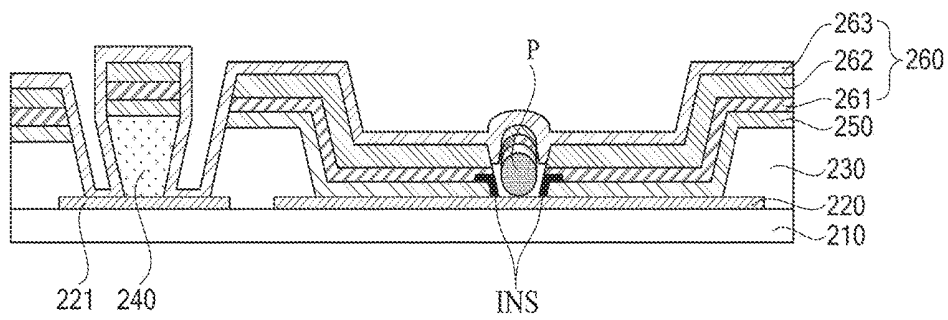


FIG. 3

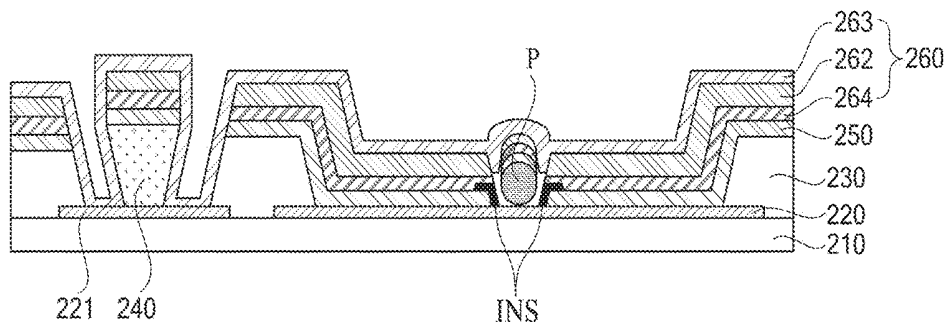


FIG. 4A

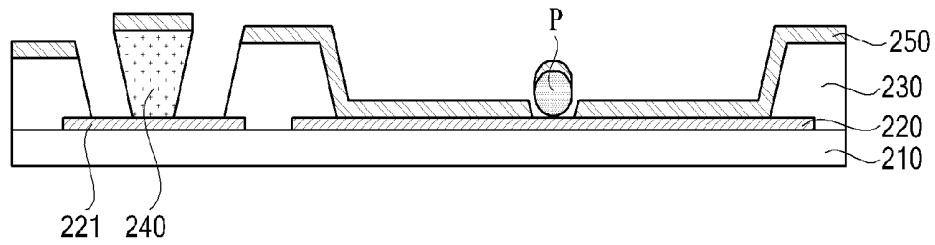


FIG. 4B

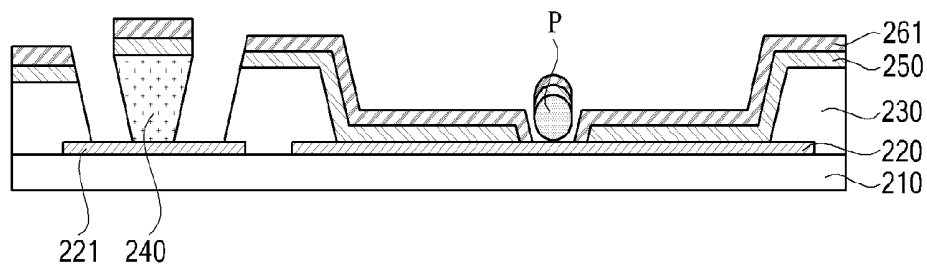


FIG. 4C

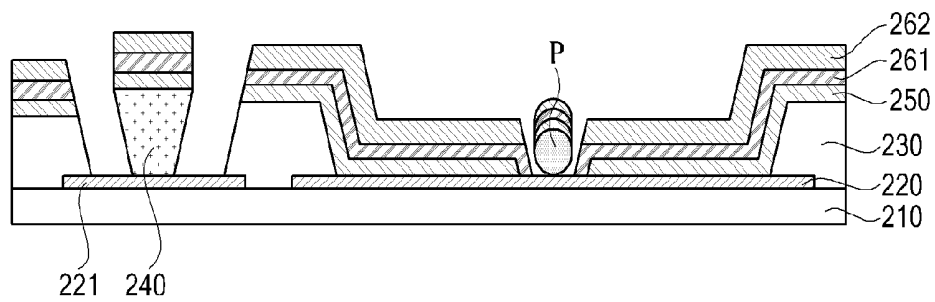


FIG. 4D

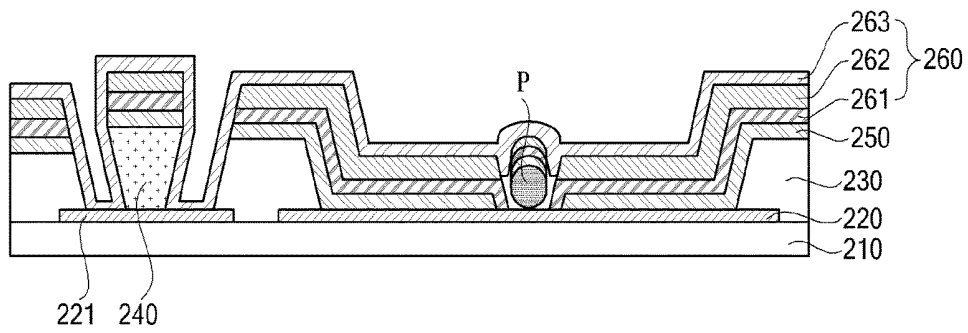


FIG. 4E

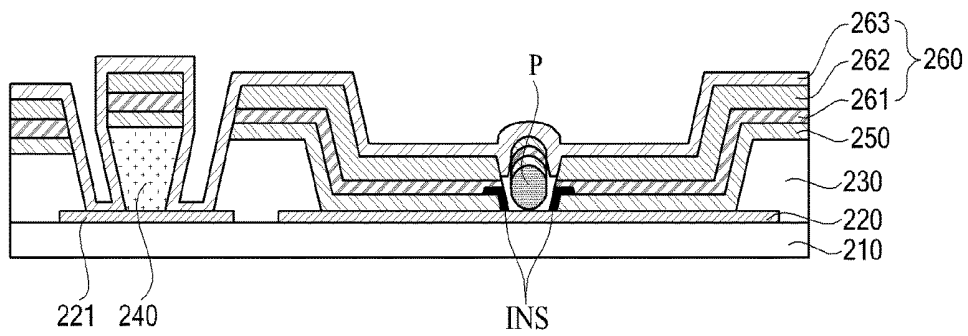
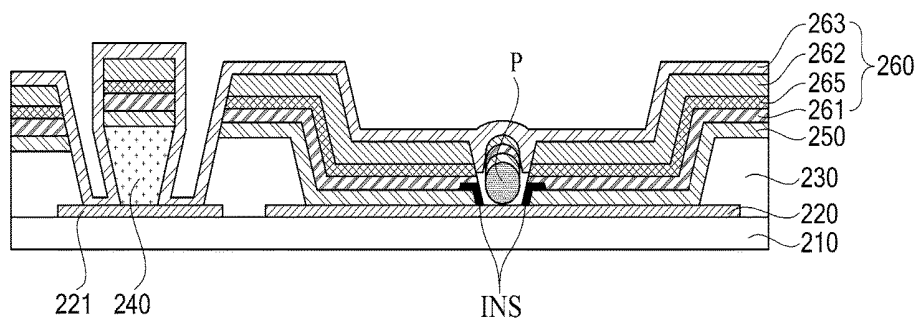


FIG. 5



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ORGANIC LIGHT EMITTING DISPLAY DEVICE WITH INSULATING PART AND METHOD OF MANUFACTURING THE SAME

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims the benefit of the Korean Patent Application No. 10-2013-0169483 filed on Dec. 31, 2013 and Korean Patent Application No. 10-2014-0049850 filed on Apr. 25, 2014, which are hereby incorporated by reference as if fully set forth herein.

BACKGROUND

Technical Field

The present disclosure relates to an organic light emitting display device and a method of manufacturing the same, and more particularly, to an active matrix (AM) organic light emitting display device and a method of manufacturing the same.

Discussion of the Related Art

Flat panel display devices, which are light and thin, are being actively developed. Representative examples of the flat panel display devices include liquid crystal display (LCD) devices and organic light emitting display devices.

The organic light emitting display devices do not use a separate light source such as a backlight applied to the LCD devices, and thus are thinner, have lower power consumption, and good color reproducibility. Accordingly, the organic light emitting display devices provide a relatively sharper image.

In an active matrix organic light emitting display device that is a type of the organic light emitting display device, a pixel is independently driven, and includes three sub-pixels of red, green, and blue.

Each of the three sub-pixels is defined by intersection between a gate line and a data line, and is independently driven by a driving circuit including a separate thin film transistor (TFT).

Each sub-pixel includes an organic light emitting diode (OLED) which is driven by the driving circuit. The OLED includes a pixel electrode, a common electrode, and an organic emission layer formed between two the electrodes. Foreign materials, such as a particle having a diameter greater than a thickness of the pixel electrode, the common electrode, or the organic emission layer, can occur in a process of forming the OLED.

The pixel electrode may be patterned and formed by a photolithography process. After the pixel electrode is formed, the foreign materials can remain.

There is a high possibility that the foreign materials occur in a process of forming thin layers which are formed on a substrate in common. Representative examples of the thin layers, which are formed on the substrate in common, include the organic emission layer and the common electrode.

In particular, the organic emission layer may be formed by a vacuum deposition process using a shadow mask, a laser transfer process, a thermal transfer process, or a screen printing process. Residual materials can remain after a process. Also, in a top emission type organic light emitting display device, light is output through the common electrode, and a luminance of a central portion of a screen can be reduced due to an increase in a resistance. Therefore, an auxiliary electrode connected to the common electrode may be formed in plurality at the central portion of the screen, for

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preventing luminance from being reduced due to an increase in a resistance of the central portion of the screen.

A metal oxide layer having a large step coverage may be used for connecting the common electrode to the auxiliary electrode. In this case, the metal oxide layer penetrates into a gap between foreign materials, and for this reason, a possibility that short circuit between the pixel electrode and the common electrode can more increase.

FIG. 1 is a cross-sectional view illustrating an organic light emitting display device in which a defect occurs due to a foreign material. In FIG. 1, the foreign material is illustrated as a particle P.

Referring to FIG. 1, the particle P can occur in a process of forming a pixel electrode 120, an organic emission layer 150, and a common electrode 160 which are formed on a substrate 110. When a diameter of the particle P is greater than a thickness of each of the pixel electrode 120, the organic emission layer 150, and the common electrode 160, the pixel electrode 120 is connected to the common electrode 160, causing short circuit. Here, the common electrode 160 may include a metal layer 161 and a conductive organic layer 162. In FIG. 1, reference numeral 121 refers to an auxiliary electrode, reference numeral 130 refers to a bank layer, and reference numeral 140 refers to a partition layer.

When short circuit occurs between the pixel electrode 120 and the common electrode 160, a current does not flow in the organic emission layer 150, and for this reason, a whole pixel cannot emit light. Therefore, a pixel in which short circuit occurs between the pixel electrode 120 and the common electrode 160 may be a defective pixel which cannot emit light.

SUMMARY

Accordingly, the present disclosure is directed to provide an organic light emitting display device and a method of manufacturing the same that substantially obviate one or more problems due to limitations and disadvantages of the related art.

An aspect of the present disclosure is directed to provide an organic light emitting display device that can prevent a defective pixel from occurring.

Additional advantages and features of the disclosure will be set forth in part in the description which follows and in part will become apparent to those having ordinary skill in the art upon examination of the following or may be learned from practice of the disclosure. The objectives and other advantages of the disclosure may be realized and attained by the structure particularly pointed out in the written description and claims hereof as well as the appended drawings.

To achieve these and other advantages and in accordance with the purpose of the disclosure, as embodied and broadly described herein, there is provided an organic light emitting display device including: a substrate; a pixel electrode disposed on the substrate; an organic emission layer disposed on the pixel electrode; a common electrode including a metal layer disposed on the organic emission layer, a conductive organic layer disposed on the metal layer, and a first metal oxide layer disposed on the conductive organic layer; and an insulating part formed in a part of an area of a surface of the metal layer, the part of the area of the surface having been exposed to a foreign material, wherein the insulating part insulates the pixel electrode from the common electrode.

In another aspect of the present disclosure, there is provided a method of forming an organic light emitting display device including: forming a pixel electrode on a

substrate; forming an organic emission layer on the pixel electrode; forming a common electrode that includes a metal layer disposed on the organic emission layer, a conductive organic layer disposed on the metal layer, and a first metal oxide layer disposed on the conductive organic layer; and forming an insulating part in a part of an area of a surface of the metal layer having been exposed to a foreign material.

It is to be understood that both the foregoing general description and the following detailed description of the present disclosure are exemplary and explanatory and are intended to provide further explanation of the disclosure as claimed.

BRIEF DESCRIPTION OF THE DRAWINGS

The accompanying drawings, which are included to provide a further understanding of the disclosure and are incorporated in and constitute a part of this application, illustrate embodiments of the disclosure and together with the description serve to explain the principle of the disclosure. In the drawings:

FIG. 1 is a cross-sectional view illustrating an organic light emitting display device in which a defect occurs due to a foreign material;

FIG. 2 is a cross-sectional view illustrating an organic light emitting display device according to an embodiment of the present disclosure;

FIG. 3 is a cross-sectional view illustrating an organic light emitting display device according to another embodiment of the present disclosure; and

FIGS. 4A to 4E are cross-sectional views illustrating a method of manufacturing an organic light emitting display device according to an embodiment of the present disclosure, and FIG. 5 is a cross-sectional view illustrating an organic light emitting display device according to another embodiment of the present disclosure.

DETAILED DESCRIPTION

Reference will now be made in detail to the exemplary embodiments of the present disclosure, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers will be used throughout the drawings to refer to the same or like parts.

Hereinafter, embodiments of the present disclosure will be described in detail with reference to the accompanying drawings.

FIG. 2 is a cross-sectional view illustrating an organic light emitting display device according to an embodiment of the present disclosure. As illustrated in FIG. 2, the organic light emitting display device according to an embodiment of the present disclosure includes a substrate 210, a pixel electrode 220, a common electrode 260, and an organic emission layer 250 disposed between the pixel electrode 220 and the common electrode 260.

First, the substrate 210 may include one selected from glass, plastic, and metal. The substrate 210 may be implemented as a flexible substrate that is formed of one of the materials.

The plastic may be one selected from polyethersulphone (PES), polyacrylate (PAR), polyetherimide (PEI), polyethylenenapthalate (PEN), polyethylene terephthalate (PET), polyphenylene sulfide (PPS), polyallylate, polyimide, polycarbonate (PC), cellulose triacetate (TAC), and cellulose acetate propionate (CAP).

Subsequently, the pixel electrode 220 is disposed on the substrate 210. In the present embodiment, the pixel electrode

220 may be an anode electrode, and may be formed of a single layer or a multi-layer that includes at least one selected from indium, silver (Ag), zinc, tin, aluminum zinc oxide (AZO), gallium zinc oxide (GZO), zinc oxide (ZnO), indium tin oxide (ITO), indium zinc oxide (IZO), and indium tin zinc oxide (ITZO). When the pixel electrode 220 is formed of a multi-layer, the pixel electrode 220 may include at least one transparent conductive oxide layer and at least one metal layer.

The transparent conductive oxide layer has a high work function, and thus may supply a positive hole to the organic emission layer 250. The transparent conductive oxide layer may contact the organic emission layer 250.

Subsequently, the organic emission layer 250 is disposed on the pixel electrode 220.

The organic emission layer 250 is formed of a thin layer of an organic material, and generates light by using a positive hole and an electron which are injected through the pixel electrode 220 and the common electrode 260. Although not shown in FIG. 2, the organic emission layer 250 may include a hole injection layer (HIL), a hole transport layer (HTL), an emission layer (EML), and an electron transport layer (ETL).

In the present embodiment, the pixel electrode 220 acts as the anode electrode, and the common electrode 260 may act as a cathode electrode. However, the present embodiment is not limited thereto.

The HIL is a buffering layer that lowers an energy barrier between the pixel electrode 220 and the EML to enhance efficiency in which a positive hole is injected from the pixel electrode 220. The HTL constrains an electron, which is injected from the common electrode 260 and is transported to the EML, in the EML to increase efficiency in which an electron and a positive hole are recombined in the EML. Similarly, the ETL is a buffering layer that lowers an energy barrier between the common electrode 260 and the EML. The ETL enhances efficiency in which an electron is injected from the common electrode 260, and constrains a positive hole, transported to the EML, in the EML to increase efficiency in which an electron and a positive hole are recombined in the EML. The EML is formed of a thin layer of a low-molecular organic material or a polymer-based organic material. In the EML, a positive hole and an electron which are injected from the pixel electrode 220 and the common electrode 260 and transported to the EML are recombined to generate an exciton, and energy which is emitted by shifting the exciton from an excited state to a ground state is generated as light. In this case, a color of emitted light is changed according to band-gap energy of an organic material forming the EML.

Subsequently, the common electrode 260 is disposed on the organic emission layer 250. In more detail, the common electrode 260 may include a metal layer 261 disposed on the organic emission layer 250, a conductive organic layer 262 disposed on the metal layer 261, and a first metal oxide layer 263 disposed on the conductive organic layer 262.

Since the common electrode 260 acts as the cathode electrode, the common electrode 260 may supply an electron to the organic emission layer 250. In order to supply an electron to the organic emission layer 250, a work function of an area contacting the organic emission layer 250 may be relatively lower than that of the pixel electrode 220. Therefore, metal that is a material having a low work function may be disposed in an area contacting the organic emission layer 250. Therefore, the metal layer 261 is disposed in the area

contacting the organic emission layer **250**. That is, the metal layer **261** may be disposed on the organic emission layer **250**.

The metal layer **261** may include one or at least one selected from silver (Ag), magnesium (Mg), calcium (Ca), aluminum (Al), lithium (Li), and neodymium (Nd). The metal layer **261** may be formed of one of the following alloys, or may include one or at least one of the following alloys. Examples of the alloys may include LiF/Al, CsF/Al, Mg:Ag, Ca/Ag, Ca:Ag, LiF/Mg:Ag, LiF/Ca/Ag, and LiF/Ca:Ag, but are not limited thereto.

Moreover, the metal layer **261** may include an insulating part INS formed at a part of a surface which is exposed to a foreign material in a whole surface of the metal layer **261**. There is a possibility that an undesired foreign material occurs in a process of forming the pixel electrode **220**, the organic emission layer **250**, or the common electrode **260**. As illustrated in FIG. 2, when a particle P which is greater than a thickness of each thin layer is generated, short circuit can occur because the pixel electrode **220** is connected to the common electrode **260**, and particularly, the metal layer **261**. In this case, a pixel in which a foreign material is disposed cannot emit light.

Therefore, forming of the common electrode **260** is completed, and then, when short circuit between the pixel electrode **220** and the common electrode **260** occurs in an area where the particle P is disposed, the metal layer **261** in an area where the pixel electrode **220** contacts the common electrode **260** is oxidized by applying a reverse voltage to the pixel electrode **220** and the common electrode **260**, thereby forming the insulating part INS. Therefore, the insulating part INS prevents short circuit from occurring between the pixel electrode **220** and the common electrode **260**, and insulates the pixel electrode **220** from the common electrode **260**. The metal layer **261** in an area where the pixel electrode **220** contacts the common electrode **260**, as illustrated in FIG. 2, may be a surface of the metal layer **261** in the area where the particle P is disposed.

The conductive organic layer **262** is disposed on the metal layer **261**. The conductive organic layer **262** may be formed of a conductive organic material, or may include a conductive organic material. Since the conductive organic layer **262** should have conductivity, the conductive organic layer **262** may include one of materials forming the organic emission layer **250**, or may be formed of the same material as that of the organic emission layer **250**.

A thickness of the conductive organic layer **262** may be 100 Å to 5,000 Å. The conductive organic layer **262** is formed for preventing the first metal oxide layer **262** from being connected to or communicating with the pixel electrode **220**, and thus can prevent the first metal oxide layer **262** from penetrating into a gap between the particle P and the conductive organic layer **262** in a state of maintaining the thickness or more.

The conductive organic layer **262** allows the metal layer **261**, which is a lowermost layer configuring the common electrode **260**, to communicate with the first metal oxide layer **263** that is an uppermost layer of the common electrode **260**, and thus increases a volume of the common electrode **260**, thereby preventing a resistance from increasing and preventing a voltage from being dropped. In particular, the first metal oxide layer **263** may be connected to a below-described auxiliary electrode **221**, and thus, the conductive organic layer **262** allowing the metal layer **261** to communicate with the first metal oxide layer **263** is very important for increasing a resistance and dropping a voltage.

The auxiliary electrode **221** is disposed on the substrate **210**, and may be supplied with the same voltage as a voltage applied to the common electrode **260**. In the present embodiment, the common electrode **260** acts as the cathode electrode, and may be connected to a low-level voltage terminal (Vss).

Therefore, the auxiliary electrode **221** may be connected to the low-level voltage terminal (Vss). The pixel electrode **220** acts as the anode electrode, and may be connected to a high-level voltage terminal (Vdd).

Moreover, the auxiliary electrode **221** may be formed simultaneously with a process of forming the pixel electrode **220**, and thus may be disposed on the same layer as that of the pixel electrode **220**.

That is, the auxiliary electrode **221** may be formed of the same material as that of the pixel electrode **220**, or may include the same material as that of the pixel electrode **220**.

When the pixel electrode **220** is formed of a single layer, the auxiliary electrode **221** may be formed of the same material as that of the single layer. When the pixel electrode **220** is formed by stacking a plurality of thin layers, the auxiliary electrode **221** may be formed of the same material as that of one of the thin layers.

The auxiliary electrode **221** is connected to the common electrode **260** so as to prevent a voltage of the common electrode **260** from being dropped, and particularly, may be connected to the first metal oxide layer **263**. The common electrode **260** may be connected to the low-level voltage terminal (Vss) at a pad part in a non-display area (not shown) that is an edge area of the substrate **210**, and may not be connected to the low-level voltage terminal (Vss) at a central portion of the substrate **210**. Therefore, a resistance of the common electrode **260** increases at the central portion of the auxiliary electrode **221**, causing a drop of a voltage. To solve such a problem, the low-level voltage terminal (Vss) is connected to the auxiliary electrode **221**, and the auxiliary electrode **221** is connected to the common electrode **260**, thereby preventing a voltage from being dropped.

As described above, in order for the auxiliary electrode **221** to be connected to the common electrode **260** with the organic emission layer **250** therebetween, a partition layer **240** may be formed in an area where a bank layer **230** outside an emission area is disposed, and the auxiliary electrode **221** may be connected to the common electrode **260** through the partition layer **240**. The partition layer **240** may be formed in a reverse taper shape between adjacent bank layers **230**. An interval between the partition layer **240** and the bank layer **230** is small, and thus, the organic emission layer **250** and the metal layer **261** and conductive organic layer **262** of the common electrode **260** are coated on only the partition layer **240** without being connected to the auxiliary electrode **221**.

However, when the first metal oxide layer **263** is formed by a sputtering process, a step coverage characteristic of the first metal oxide layer **263** becomes far better, and thus, the first metal oxide layer **263** may penetrate into a gap between the partition layer **240** and the bank layer **230** to form a thin layer. Therefore, the first metal oxide layer **263** may be connected to the auxiliary electrode **221**.

Although not shown in FIG. 2 but shown in FIG. 5, the common electrode **260** may further include a second metal oxide layer **265** disposed between the metal layer **261** and the conductive organic layer **262**.

When the second metal oxide layer **265** is included in the common electrode **260**, electron injection efficiency can be enhanced, and a sheet resistance can increase.

The second metal oxide layer **265** may be thinly formed so as not to be short-circuited in connection with the pixel electrode **220**, and may be formed to a thickness of 10 Å to 500 Å.

In an embodiment in where the second metal oxide layer **265** is formed, the conductive organic layer **262** may be formed to a thickness of 100 Å to 10,000 Å, and the first metal oxide layer **263** may be formed to a thickness of 100 Å to 5,000 Å.

FIG. 3 is a cross-sectional view illustrating an organic light emitting display device according to another embodiment of the present disclosure.

Referring to FIG. 3, in another embodiment of the present disclosure, a common electrode **260** does not include the metal layer of FIG. 2, and may include a first metal oxide layer **263**, a conductive organic layer **262**, and a second metal oxide layer **264**.

When the common electrode **260** does not include the metal layer **261**, a pixel electrode **220** may be connected to the common electrode **260** by a particle P, and in detail, the pixel electrode **220** may be connected to the second metal oxide layer **264** at a peripheral portion of the particle P.

The pixel electrode **220** may be connected to, through the second metal oxide layer **264**, the common electrode **260** at the peripheral portion of the particle P by the particle P. Therefore, the second metal oxide layer **264** in an area where the pixel electrode **220** is connected to the common electrode **260** by the particle P is broken by a voltage applied to the pixel electrode **220** and the common electrode **260**, and thus, an insulating part INS between the common electrode **260** and the pixel electrode **220** is formed at the peripheral portion of the particle P.

FIGS. 4A to 4E are cross-sectional views illustrating a method of manufacturing an organic light emitting display device according to an embodiment of the present disclosure.

As illustrated in FIG. 4A, the pixel electrode **220** is formed on the substrate **210**. The auxiliary electrode **221** may be formed simultaneously with a process of forming the pixel electrode **220**. However, the present embodiment is not limited thereto, and the auxiliary electrode **221** may be formed separately from the pixel electrode **220**.

Subsequently, the bank layer **230** is formed on the pixel electrode **220**. The bank layer **230** overlaps a part of an edge of the pixel electrode **220**, and defines an emission area in which the pixel electrode **220** contacts the organic emission layer **250**. The bank layer **230** may overlap a part of an edge of the auxiliary electrode **221**. The partition layer **240** is disposed on the auxiliary electrode **221** exposed by the bank layer **230**. The partition layer **240** has a reverse taper shape, and the bank layer **230** and the partition layer **240** are separated from each other to form a space into which the first metal oxide layer **263** to be formed later penetrates.

After the bank layer **230** and the partition layer **240** are formed, the organic emission layer **250** is formed on the pixel electrode **220**. The organic emission layer **250** is formed all over the substrate **210** in common, and thus may be formed on the bank layer **230** and the partition layer **240**. However, the organic emission layer **250** does not penetrate into the space between the bank layer **230** and the partition layer **240** to form a thin layer.

The organic emission layer **250** may be formed by a vacuum deposition process using a shadow mask, a laser transfer process, a thermal transfer process, or a screen printing process. When the particle P is formed on the pixel electrode **220**, the organic emission layer **250** may not be formed in a peripheral area of the particle P.

Subsequently, as illustrated in FIG. 4B, the metal layer **261** may be formed on the organic emission layer **250**. Since a step coverage characteristic of the metal layer **261** is not good, the metal layer **261** may be formed in the same area as that of the organic emission layer **250**. The metal layer **261** may include one or at least one selected from silver (Ag), magnesium (Mg), calcium (Ca), aluminum (Al), lithium (Li), and neodymium (Nd). The metal layer **261** may be formed of one of the following alloys, or may include alloys such as LiF/Al, CsF/Al, Mg:Ag, Ca/Ag, Ca:Ag, LiF/Mg:Ag, LiF/Ca/Ag, and LiF/Ca:Ag.

Subsequently, as illustrated in FIG. 4C, the conductive organic layer **262** may be formed on the metal layer **261**. The conductive organic layer **262** may be formed to a thickness of 100 Å to 5,000 Å. The conductive organic layer **262** may be formed of the same material as that of the organic emission layer **250**, or may include at least one the same material.

Although not shown, the second metal oxide layer (not shown) disposed between the metal layer **261** and the conductive organic layer **262** may be further formed. The second metal oxide layer (not shown) may be formed of the same material as that of the first metal oxide layer **263**, and may be thinly formed so as not to be short-circuited with the pixel electrode **220**. For example, the second metal oxide layer may be formed to a thickness of 10 Å to 500 Å.

Subsequently, as illustrated in FIG. 4D, the first metal oxide layer **263** may be formed on the conductive organic layer **262**. The first metal oxide layer **263** may be formed by the sputtering process, and thus, a step coverage characteristic of the first metal oxide layer **263** can be more enhanced. The first metal oxide layer **263** is connected to the auxiliary electrode **221**, but is not connected to the pixel electrode **220**.

Finally, as illustrated in FIG. 4E, the common electrode **260** including the conductive organic layer **262** and the first metal oxide layer **263** is formed, and then, by applying a reverse voltage to the pixel electrode **220** and the common electrode **260**, the insulating part INS is formed at a surface of the metal layer **261** exposed to the particle P that is a foreign material. In the present embodiment, since the pixel electrode **220** acts as the anode electrode and the common electrode **260** acts as the cathode electrode, by applying a low-level voltage to the pixel electrode **220** and applying a high-level voltage to the common electrode **260** to thereby apply a reverse voltage, the metal layer **261** may be oxidized, and thus, the insulating part INS may be formed at the surface of the metal layer **261** exposed to a foreign material.

Moreover, even when the first metal oxide layer **263** penetrates up to a lower portion of the particle P and thus a portion of the first metal oxide layer **263** is connected to the pixel electrode **220**, short circuit between the pixel electrode **220** and the common electrode **260** can be prevented because an area in which the first metal oxide layer **263** is connected to the pixel electrode **220** is insulated by an operation of applying the reverse voltage.

As described above, the insulating part INS is formed between the pixel electrode **220** and the common electrode **260**, and thus, even when a foreign material such as the particle P occurs in a process of forming an OLED including the organic emission layer, the insulating part INS prevents short circuit from occurring. Accordingly, an only area in which the particle P occurs in a pixel does not illuminate and appears dark (or black), and the other area of the pixel is normally driven, thereby preventing a defective pixel from being formed. Also, the conductive organic layer **262** is formed between the organic emission layer **250** and the

common electrode **260**, and prevents the first metal oxide layer **263** included in the common electrode **260** from being connected to the pixel electrode **220** through a space between the particle P and the organic emission layer **250**, thereby preventing short circuit from occurring between the pixel electrode **220** and the first metal oxide layer **263**.

According to the embodiments of the present disclosure, the insulating part is formed between the pixel electrode and the common electrode, and thus, even when a foreign material such as a particle occurs in a process of forming the OLED including the organic emission layer, the insulating part prevents short circuit from occurring. Accordingly, an only area in which a foreign material occurs in a pixel is blackened, and the other area of the pixel is normally driven.

Moreover, according to the embodiments of the present disclosure, since an only area in which a foreign material occurs is blackened and the other area of the pixel is normally driven, a defective pixel can be prevented from occurring.

Moreover, according to the embodiments of the present disclosure, the conductive organic layer is formed between the organic emission layer and the common electrode, and prevents the first metal oxide layer included in the common electrode from being connected to the pixel electrode, thereby preventing short circuit from occurring between the pixel electrode and the first metal oxide layer.

What is claimed is:

1. An organic light emitting display device comprising:
a substrate;
a pixel electrode disposed on the substrate;
an organic emission layer disposed on the pixel electrode;
and
a common electrode including a metal layer disposed on the organic emission layer, a conductive organic layer disposed on the metal layer, and a first metal oxide layer disposed on the conductive organic layer,
wherein the metal layer includes an insulating portion that extends toward the pixel electrode and directly contacts the pixel electrode.
2. The organic light emitting display device of claim 1, further comprising an auxiliary electrode disposed on the substrate, wherein the auxiliary electrode is connected to the first metal oxide layer.
3. The organic light emitting display device of claim 2, wherein the auxiliary electrode is supplied with a voltage equal to a voltage supplied to the common electrode.
4. The organic light emitting display device of claim 2, wherein the auxiliary electrode is disposed on the same layer as a layer of the pixel electrode.
5. The organic light emitting display device of claim 1, wherein a thickness of the first metal oxide layer is 100 Å to 5,000 Å.
6. The organic light emitting display device of claim 1, wherein the organic emission layer and the conductive organic layer are formed of the same material.
7. The organic light emitting display device of claim 1, wherein a thickness of the conductive organic layer is 100 Å to 10,000 Å.

8. The organic light emitting display device of claim 1, wherein the common electrode further comprises a second metal oxide layer disposed between the metal layer and the conductive organic layer.

9. The organic light emitting display device of claim 8, wherein a thickness of the second metal oxide layer is 10 Å to 500 Å.

10. The organic light emitting display device of claim 1, wherein the metal layer includes another insulating portion that extends toward the pixel electrode and directly contacts the pixel electrode.

11. An organic light emitting display device comprising:
a pixel electrode disposed on a substrate;

an organic emission layer disposed on the pixel electrode;
a first metal oxide layer disposed on the organic emission layer;

a conductive organic layer disposed on the first metal oxide layer; and

a second metal oxide layer disposed on the conductive organic layer,

wherein the first metal oxide layer includes an insulating portion that extends toward the pixel electrode and directly contacts the pixel electrode.

12. The organic light emitting display device of claim 11, wherein a thickness of the first metal oxide layer is 100 Å to 5,000 Å.

13. The organic light emitting display device of claim 11, wherein the organic emission layer and the conductive organic layer are formed of a same material.

14. The organic light emitting display device of claim 11, wherein a thickness of the conductive organic layer is 100 Å to 10,000 Å.

15. The organic light emitting display device of claim 11, wherein a thickness of the second metal oxide layer is 10 Å to 500 Å.

16. The organic light emitting display device of claim 11, wherein the first metal oxide layer includes another insulating portion that extends toward the pixel electrode and directly contacts the pixel electrode.

17. A method of forming an organic light emitting display device, the method comprising:

forming a pixel electrode on a substrate;

forming an organic emission layer on the pixel electrode;

forming a common electrode that includes a metal layer disposed on the organic emission layer, a conductive organic layer disposed on the metal layer, and a first metal oxide layer disposed on the conductive organic layer; and

modifying a portion of the metal layer to be insulating, the portion of the metal layer extending towards the pixel electrode and directly contacting the pixel electrode.

18. The method of claim 17, further comprising forming an auxiliary electrode on the substrate, wherein the auxiliary electrode is connected to the first metal oxide layer.

19. The method of claim 17, wherein modifying the portion of the metal layer comprises applying a reverse voltage to the pixel electrode and the metal layer.

20. The method of claim 17, further comprising forming a second metal oxide layer between the metal layer and the conductive organic layer.

* * * * *

专利名称(译)	具有绝缘部件的有机发光显示装置及其制造方法		
公开(公告)号	US9577207	公开(公告)日	2017-02-21
申请号	US14/585428	申请日	2014-12-30
[标]申请(专利权)人(译)	乐金显示有限公司		
申请(专利权)人(译)	LG DISPLAY CO. , LTD.		
当前申请(专利权)人(译)	LG DISPLAY CO. , LTD.		
[标]发明人	KIM YOUNG MI HEO JOON YOUNG LEE YEON KYEONG		
发明人	KIM, YOUNG MI HEO, JOON YOUNG LEE, YEON KYEONG		
IPC分类号	H01L51/52 H01L27/32		
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审查员(译)	艾哈迈迪MOHSEN		
优先权	1020130169483 2013-12-31 KR 1020140049850 2014-04-25 KR		
其他公开文献	US20150188077A1		
外部链接	Espacenet USPTO		

摘要(译)

公开了一种有机发光显示装置。有机发光显示装置包括基板，设置在基板上的像素电极，设置在像素电极上的有机发光层，包括设置在有机发光层上的金属层的公共电极，设置在金属上的导电有机层层和设置在导电有机层上的第一金属氧化物层，以及形成在金属层的暴露于异物的表面的一部分区域中的绝缘部分。绝缘部分使像素电极与公共电极绝缘。

